

Special Issue

Heterogeneous Integration and Advanced Packaging for Micro and Nanosystems

Message from the Guest Editor

Over the past several decades, heterogeneous integration and advanced packaging technologies have been established in the fields of MEMS/NEMS, photonics and electronics. Even now, these technologies continue to advance toward the miniaturization, cost reduction, functional diversification, and performance enhancement of these micro- and nanodevices. The scope of this Special Issue of *Sensors* is to highlight the continuous growth and latest advances in the field of heterogeneous integration and advanced packaging technologies for micro- and nanosystems by collating original research papers, short communications, and review articles. Topics include but not are limited to the following:

- Heterogeneous integration;
- Advanced packaging;
- Wafer and die bonding;
- Wafer-level packaging;
- Hermetic sealing;
- Micro- and nanosensors;
- MEMS/NEMS;
- Opto-electronic integration.

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Message from the Editor-in-Chief

Sensors is a leading journal devoted to fast publication of the latest achievements of technological developments and scientific research in the huge area of physical, chemical and biochemical sensors, including remote sensing and sensor networks. Both experimental and theoretical papers are published, including all aspects of sensor design, technology, proof of concept and application. Sensors organizes Special Issues devoted to specific sensing areas and applications each year.

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